

REMARKS

The application has been amended to place the application in condition for allowance at the time of the next Official Action.

Claims 1-17, 23 and 24 were previously pending in the application. Claims 14-17 and 24 are cancelled and new claims 25-29 are added. Therefore, claims 1-13, 23 and 25-29 are presented for consideration. Applicant notes with appreciation the indication that claims 3-5, 7-13 and 15-17 are allowable.

Canceling claim 14 is believed to address the claim objection noted in the Official Action.

Claims 1, 6, 14, 23 and 24 are rejected as anticipated by CHUN 6,043,430. This rejection is respectfully traversed.

Independent claims 1 and 23 are amended and recite that the outer portion of the lead element is substantially coplanar with the plate-like mount. Claim 1 is also amended to recite that the inner portion of the lead element is spaced apart from the top surface of the semiconductor chip without being mechanically connected to the chip. Support for the limitations can be found on page 2, lines 15-21 of the application as filed and in Figure 7, for example.

Figures 5, 6A-6D and 7 of CHUN are noted in the Official Action as providing support for the recited limitations.

However, the reference does not appear to teach that for which it is offered and in any event does not meet each of the recited limitations.

Element 23 of CHUN is indicated in the Official Action as a plate-like mount. Column 3, lines 1-3 of CHUN disclose element 23 as a lower lead attached to a lower side of the chip 21 by an adhesive. Accordingly, it does not appear that element 23 of CHUN meets the recited at least one plate-like mount.

Nevertheless, even if one were consider element 23 as a plate-like mount, the outer portion of lead element 23' is not substantially coplanar with the plate-like mount as recited. Rather, as noted in the Official Action, element 23' is in contact with (above) element 23 and thus is not substantially coplanar therewith.

In addition, each of the lead elements (23') of CHUN is mechanically connected to chip 21 using insulating adhesive 22, 22'. CHUN does not disclose or suggest that the lead element is spaced apart from the top surface of the semiconductor chip without being mechanically connected to the chip as recited.

As the reference does not disclose that which is recited, the anticipation rejection is not viable. Reconsideration and withdrawal of the rejection are respectfully requested.

Claim 2 is rejected as unpatentable over CHUN in view of CASTO 5,172,214. This rejection is respectfully traversed.

CASTO in Figure 1, for example, shows a lead 66 mechanically connected to a semiconductor die 64 using a TAB bond 73 or other type of lead-on-chip bond. CASTO does not teach or suggest that the lead element is spaced apart from the top surface of the semiconductor chip without being mechanically connected to the chip as recited in claim 1. As set forth above, CHUN does not disclose or suggest what is recited in claim 1. Since claim 2 depends from claim 1 and further defines the invention, the proposed combination of references would not have rendered obvious claim 2.

New claims 25-29 are added. Support for the new claims can be found in Figures 5-7. The new claims are believed patentable at least for the reasons that the allowable claims are patentable.

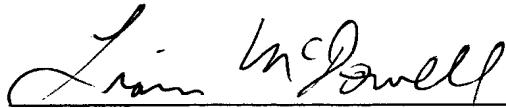
In view of the present amendment and the foregoing remarks, therefore, it is believed that the present application has been placed in condition for allowance. Reconsideration and allowance are respectfully requested.

The Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any

overpayment to Deposit Account No. 25-0120 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17.

Respectfully submitted,

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